PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
William Wu Shen	07/02/2013
Yun-Han Lee	07/02/2013
Chin-Chou Liu	07/02/2013
Hsien-Hsin Lee	07/02/2013
Chung-Sheng Yuan	07/09/2013
Chao-Yang Yeh	07/02/2013
Wei-Cheng Wu	07/03/2013
Ching-Fang Chen	07/05/2013

RECEIVING PARTY DATA

Name:	Taiwan Semiconductor Manufacturing Company Limited
Street Address:	No. 8, Li-Hsin Road 6, Hsin-Chu Science Park
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300-77

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13833724

OP $40.00 13833724

CORRESPONDENCE DATA

Fax Number:
Correspondence will be sent via US Mail when the fax attempt is unsuccessful.
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Correspondent Name: Cooper Legal Group LLC
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ATTORNEY DOCKET NUMBER:	TSMC2012-1256

NAME OF SUBMITTER:	William J. Cooper
Signature:	/William J. Cooper/
Date:	09/18/2013
Total Attachments: 3 source=ExecutedAssignment#page1.tif source=ExecutedAssignment#page2.tif source=ExecutedAssignment#page3.tif	

ASSIGNMENT

For good and valuable consideration received of the hereinafter named assignee, receipt of which is hereby acknowledged, the undersigned

William Wu Shen
Hsinchu City, TW

Yun-Han Lee
Baoshan Township, TW

Chin-Chou Liu
Jhubei City, TW

Hsien-Hsin Lee
Duluth, GA, USA

Chung-Sheng Yuan
Hsinchu City, TW

Chao-Yang Yeh
Luzhou City, TW

Wei-Cheng Wu
Hsinchu City, TW

Ching-Fang Chen
Taichung City

NOW, THEREFORE, for and in consideration of our employment and the salary or wages paid to us by Taiwan Semiconductor Manufacturing Company Limited, I/we, William Wu Shen, Yun-Han Lee, Chin-Chou Liu, Hsien-Hsin Lee, Chung-Sheng Yuan, Chao-Yang Yeh, Wei-Cheng Wu and Ching-Fang Chen, by these presents do sell, assign, and transfer unto said Taiwan Semiconductor Manufacturing Company Limited, a corporation organized and existing under the laws of the Republic of China, having its principal place of business at No. 8, Li-Hsin Road 6, Hsin-Chu Science Park, Hsin-Chu, Taiwan 300-77, R.O.C., is desirous of acquiring an interest therein, its successors and assigns, the entire right, title and interest, so far as concerns the United States and the Territories and Possessions thereof and all foreign countries, in and to the inventions entitled

COMMON TEMPLATE FOR ELECTRONIC ARTICLE

for which application for United States Letters Patent has been filed on ______________ under Serial No.___________, or was executed by the undersigned on the date below and is being filed concurrently herewith, said application for United States Letters Patent, any and all other applications for Letters Patent on said inventions in countries foreign to the United States, including all divisional, renewal, substitute, continuation and Convention applications based in whole or in part upon said inventions or upon said applications, and any and all Letters Patent and reissues and extensions of Letters Patent granted for said inventions or upon said applications, and every priority right that is or may be predicated upon or arise from said inventions, said applications and said Letters Patent; said assignee being hereby authorized to file patent applications in any or all countries on any or all said inventions in the name of the undersigned or in the name of said assignee or otherwise as said assignee may deem advisable, under the International Convention or otherwise; the Commissioner of Patents and Trademarks of the United States of America and the empowered officials of all other governments being hereby authorized to issue or transfer all said Letters Patent to said assignee in accordance herewith; this assignment being under covenant, not only that full power to make the same is had by the undersigned, but also that such assigned right is not encumbered by any grant, license, or other right heretofore given, and that the undersigned will do all acts reasonably serving to assure that said inventions, patent applications and Letters Patent shall be held and enjoyed by said assignee as fully and entirely as the same could have been held and enjoyed by the undersigned if this assignment had not been made, and particularly to execute and deliver to said assignee all lawful documents including petitions, specifications, oaths, assignments, invention disclaimers, and lawful affidavits in form and substance which may be requested by said assignee, to furnish said assignee with all facts relating to said inventions or the history thereof and any and all documents, photographs, models, samples or other physical exhibits which may be useful for establishing the facts of conception, disclosure and reduction to practice of said inventions, and to testify in any proceedings relating to said inventions, patent applications and Letters Patent.

✓	✓ 7/2/2013
Inventor's Signature	Date
William Wu Shen	
Printed Name in English	

✓	✓ 07/02/2013
Inventor's Signature	Date
Yun-Han Lee	
Printed Name in English	

✓ Chin-Chou Liu	✓ 7/2/2013
Inventor's Signature	Date
Chin-Chou Liu	
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✓	✓ 7/2/2013
Inventor's Signature	Date
Hsien-Hsin Lee	
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✓ Chung-Sheng Yuan	✓ 7/9/2013
Inventor's Signature	Date
Chung-Sheng Yuan	
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√Chao-Yang Yeh	√ 09/02/2013
Inventor's Signature	Date
Chao-Yang Yeh	
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√ Weicheng Wu	√ 7/3/2013
Inventor's Signature	Date
Wei-Cheng Wu	
Printed Name in English	

√Ching Fang Chen	√ 09/05/2013
Inventor's Signature	Date
Ching-Fang Chen	
Printed Name in English	